

Meet the team









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Electrical Engineering

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- → Roughly 50% of energy used within the US is used for home heating.
- → Widespread solar adoption has been causing dips in power spot price during peak production hours.
- → Energy storage has slow commercial adoption due to high prices of lithium storage + installation.

Goals and objectives

- → Provide a means of energy storage for low income consumers.
- → Create a plug and play solution for mass residential energy storage without professional installation.
- → Deliver thermal energy storage several orders of magnitude cheaper than equivalent lithium ion alternatives.

Goals and objectives

- → Create a simple user interface
- → User will be able to set desired room temperature, and charging times
- → User will be able to override the preset settings
- → Thermal Storage system will self regulate



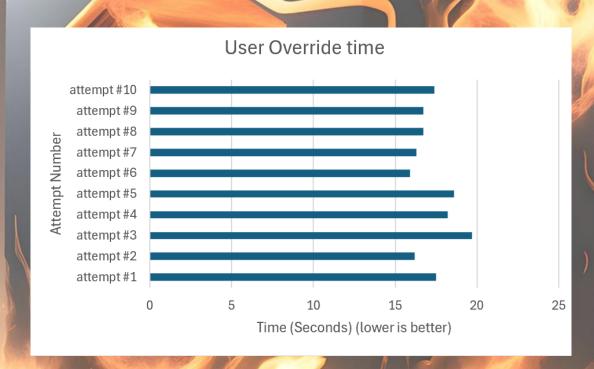
Engineering Specifications

- → Manual override for flexibility.
- → Real-Time temperature display.
- Maximum power drawn.

Specification	Description	Range/number
Charging/Heating Time	User is able to set the charging / heating time.	0-24 hours
Discharge Duration	Duration for which the battery can maintain ambient warmth.	0-24 hours
User Interface	Interface allowing the user to set charging and discharge times.	LCD 3.5"
Battery	Shows the percentage of the battery on the screen.	0-100%
Turn on/off	User is able to turn on/off overriding the schedule time.	Less than 15 seconds
External Temperature Display	Display showing the current external temperature.	0°C to 50°C
Internal Temperature Display	Display showing the current internal temperature of the sand.	0°C to 500°C
Temperature Range (Internal)	Range of temperature the internal sand can reach.	0°C to 500°C
Energy Capacity	Amount of energy the battery can store.	8KWh
Power Input	Power is required for charging the battery.	120V, 60Hz
Maximum Power Drawn	Maximum power drawn at different energy storage states.	2.5W idle, 875W charging, and 35W heating

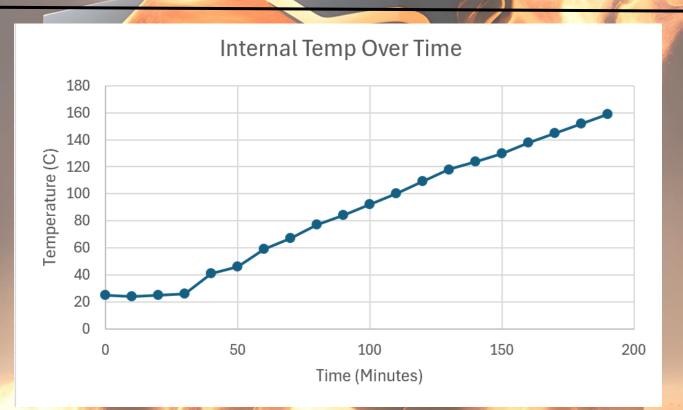
User Override





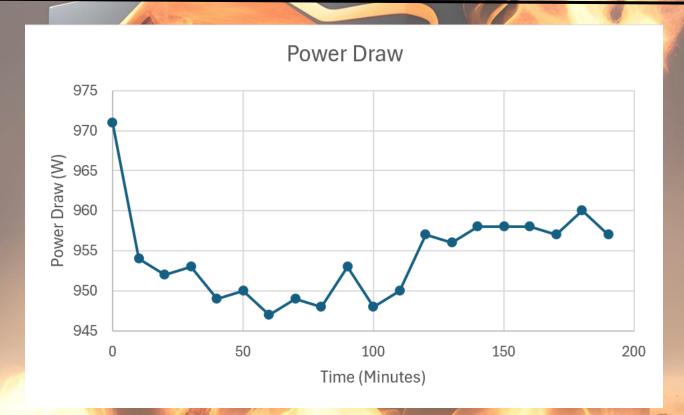






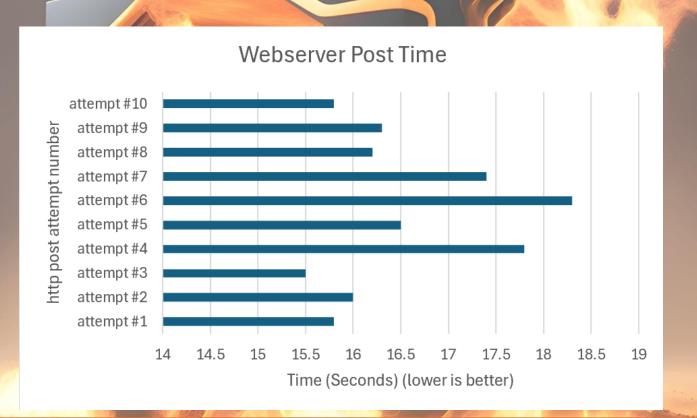














MCU

- → Strong components support and high performance.
- → Scalability and future expansion.
- → Development Ecosystem.

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	Specification	MSP430FR6989	ESP32	RP2040
	Processor	16-bit RISC	32-bit Dual-core Xtensa LX6	Dual-core ARM Cortex-M0+
ì	Clock Speed	Up to 16 MHz	Up to 240 MHz	Up to 133 MHz
	RAM	2 KB SRAM	512 KB SRAM	264 KB SRAM
130	Flash Memory	128 KB FRAM	Up to 4 MB external	Up to 2 MB external
	GPIO Pins	47	36	30
STATE OF THE OWNER, WHEN	Development Ecosystem	TI CCS, Energia	Arduino, PlatformIO	Arduino, MicroPython
	Price	\$8.68	\$3.35	\$7.74
	Best For	Battery-powered applications	IoT, Complex tasks	Versatile applications



LCD display

- Power efficiency and voltage compatibility.
- → Capacitive touchscreen with IPS quality.
- → Cost-effective solution.
- → Versatile I2C and SPI communication protocols.

	Brand	Waveshare	Adafruit	Hosyond
X	Model	4.3inch DSI QLED	3.5inch TFT Touch	3.5inch IPS SPI
	Resolution	800x480	480x320	480x320
	Display Size	4.3 inches	3.5 inches	3.5 inches
	Communication	DSI	SPI	I2C, SPI
	Touchscreen	Capacitive	Capacitive	Capacitive
A COUNTY OF THE PARTY OF THE PA	Power Consumption	1.2 watts		0.5 watts
1	Price	\$45.99	\$39.95	\$18.99
	Voltage	3.3-5V	3.3V	3.3-5V



Thermocouple

- → Accurate and sufficient temperature range.
- → Cost-effective and flexible voltage supply.
- → SPI compatibility and simplicity.

1	200			
E	Brand	Maxim Integrated	Maxim Integrated	Maxim Integrated
Ν	/lodel	MAX6675	MAX31856	MAX31865
F	Price	\$7.99	\$26.99	\$1.99
	ype of hermocouple	K type	K, J, N, R, S, and T type	K, J, N, R, S, and T type
	emperature Range	-200°C to 1024°C	-210°C to 1800°C	-200°C to 1024°C
	Digital nterface	SPI(Serial Peripheral Interface)	SPI(Serial Peripheral Interface)	SPI(Serial Peripheral Interface)
200	ower Supply oltage	3.3 or 5V	3 to 3.6V	-0.3 to 4V
F	Resolution	0.25°C / 0.45°F	0.0078125°C / 0.01283°F	0.0078125°C / 0.01283°F



Temperature sensor

- → Cost-effective and versatile.
- → Sufficient temperature and humidity ranges.
- → Simple integration and low power consumption.

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Model	Adafruit MCP98 08	DHT11	DFROBO T SEN0497	Adafruit TMP235	Adafruit AHT20
Type	Digital Temper ature Sensor	Digital Temperatu re / Humidity Sensor	Sensor Board (Analog)	Analog Temperature Sensor	Digital Temperature / Humidity Sensor
Price	\$4.99	\$9.99 per 5 pack	\$17.99	\$2.50	\$4.50
Communicati on Interface	I2C	Single-Wir e Digital	Analog Output	I2C	I2C
Temperature Range	-40°F to 257°F	32°F to 122°F	-40°F to 185°F	-40°F to 257°F	-40°F to 185°F
Temperature Resolution (Accuracy)	0.1125° F	3.6°F	Variable	0.18°F	0.55°F
Power Supply Voltage	2.7V to 5.5V	3.3V to 5.5V	3.3V to 5V	3.3V to 5V	1.8V to 3.6V
Humidity Range	N/A	20% to 95%	N/A	N/A	0% to 100%
Humidity Resolution	N/A	1%	N/A	N/A	3%



Heating element

- → Cost-effective and efficient.
- → Effective heat distribution and high efficiency.
- → Easy integration.

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	Model	Rheem Protect Copper	DERNORD Tri-Clamp Foldback	Char-Broil Universal electric	Camplux Cartridge Heater pipe fittings	Whirlpool Electric Range Stove Set
	Price	\$11.94	\$34.99	\$29.49	\$11.99/ 3 elements	\$29.56 / 4 elements
	Metal Type	Copper	Stainless Steel	Stainless Steel	Stainless Steel	Nichrome inside Steel
	Input Voltage	120V	120V	110V	110V	230V
0	Power Rating (W)	2000	1650	1500	100	1500
C.	Resistanc e (ohms)	7.2	8.73	8	121	32 and 43
	Dimension s	x 3	15.1 inches x 2.4 inches x 2.6 inches	x 10.2	1.6 inches x 0.32 inches	4 inches x 4.33 (or 6.33) inches x 0.5 inches



Heat transfer conduit

- → High heat conductivity.
- → Temperature compatibility.
- → Cost-effectiveness.

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	Type of Tubing	1 inch Metallic EMT Conduit	1 inch Copper Tubing	Stainless Steel 1 inch ThickWall Tubing	3/4 inch Aluminum Tubing
l	Material	Steel	Copper	Stainless Steel	Aluminum
	Price	\$17.47 per 10 feet	\$6.37 per foot	\$14.80 per foot	\$4.75 per foot
	Size (Diameter)	1 inch	1 inch	1 inch	3/4 inch
S. Color	Corrosion Resistance	70%	60%	90%	90%
	Flexibility	10%	40%	5%	80%
	Advantages	Durability	High thermal Conductivity, High electrical conductivity	Corrosion Resistant, Strength	Lightweight, Corrosion Resistance
	Strength	50%	70%	90%	20%
	Intended Function(s)	Electrical Wiring protection	HVAC, Water Supply	Industrial Piping, Structural Component	Structural Component, Electrical Wiring



Software Specifications

ECAD Software

- → 3D Design and Visualization.
- → Schematic-to-Layout Integration.
- → Cloud-Based collaboration and User-friendly interface.

1	Specification Altium		Fusion360	KiCad
	Flexibility	Highly adaptable, but may be too much for simple design	Less flexible than dedicated PCB tools	Flexible, but missing some advanced features
	Complexity	Many features, but it can be too much	With 3D option will increase complexity	Less features than others
	Features	Good set of features for advanced PCB design	Good selection of features for PCB design	Good set of features for a free software
NITTO AND	Integration	Excellent integration with different tools	Strong integration with Autodesk tools	Effective integration with other EDA tools
Name of Street	Easy to Use	Intuitive interface, industry-standard UI	Intuitive interface, especially for 3D	User-friendly
	Performance	Requires High-end hardware for max performance	Cloud-based nature, it may be slower	Efficient, and performs well on basic hardware
	Updates	Frequently updates and new features	Improves regularly with updates and new features	Constantly improves by open-source community



Software Specifications

Integrated development environment

- → Easy of use and quick setup.
- → Built-in ESP32 support.
- → Extensive libraries and resources.

	Specification	Arduino IDE	Visual Studio Code	IntelliJ IDEA
	Easy to Use	Beginner-friendly	Requires some setup	Complex
	Resources	Many libraries available	Extensive resources and extensions	Extensive resources
	Customization	Minimal	Highly customizable	Highly customizable
	ESP 32 Support	Built-in	Platform IO extension	Via plugins
	Initial Setup	Simple, quick setup	Requires configuration	Requires plugins and setup
18	Best For	Simple projects	Large projects	Complex projects



Software Specifications

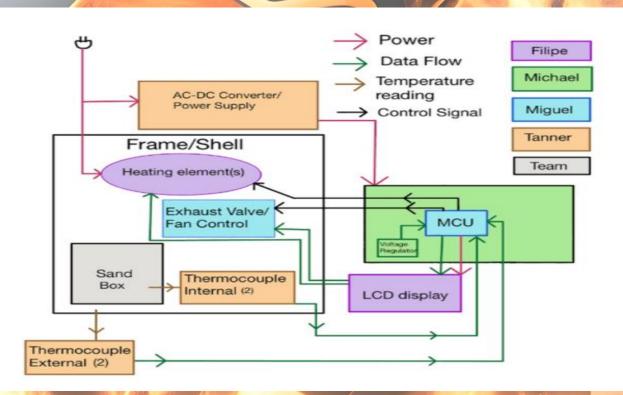
Programming language

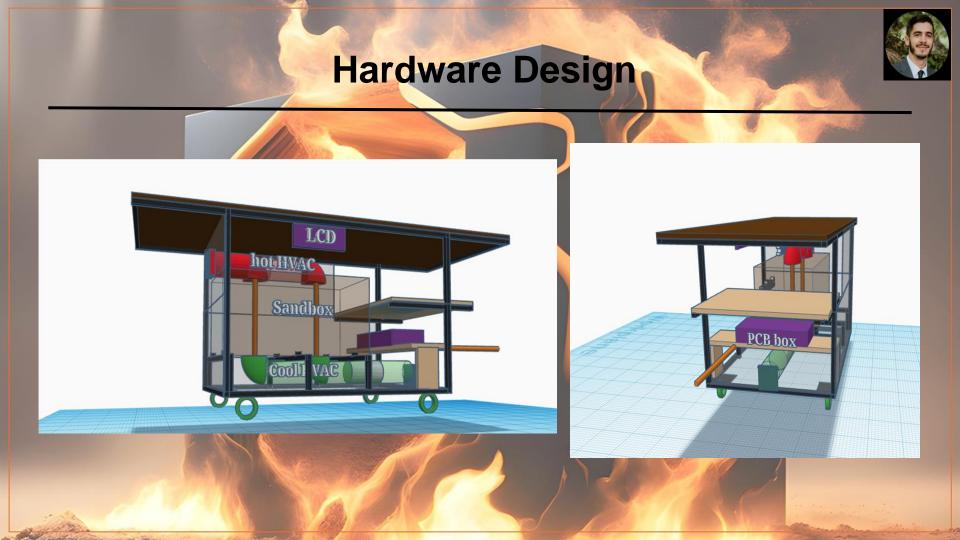
- → Powerful features.
- → Suitable for system development.
- → Balancing efficiency and capabilities.

Criterion	Python	С	C++
Easy to Use	High, simple syntax	Moderate, simple syntax, procedural	Moderate, complex syntax, object-oriented
Library	Extensive for general programming	Moderate, but extensive for embedded systems	Extensive for general and system level
Performance	Low, interpreted language	High, compiled language	High, compiled language
Memory Usage	High, less efficient	Low, very efficient	Moderate, efficient
Control	Low, high-level abstractions	High, low-level access	High, OOP features
Development Speed	Fast, many libraries	Slow, requires detailed and specific coding	Moderate, requires more code than python
Suitable for Embedded Systems	Low, barely used for microcontrollers	High, widely used for microcontrollers	High, widely used for microcontrollers



Hardware Design







Peripheral Devices



Ambient Temperature

- Provides real time readings of the room's ambient temperature
- Enables the MCU to calculate the amount of heat required to reach a desired room temperature

Internal Temperature

- Constantly monitors the internal temperature
- Alerts the MCU when the temperature falls below a set threshold, triggering a recharge of thermal energy
- Safety monitor system to shut off heating elements in case of overheating

Power/ Heat Control

- ZGT-25DD Solid State Relays
- Controls the power supply of the heating elements and regulates heat valves for release discharge
- The MCU turns on/off these relays when the condition to release heat or recharge has been met

LCD Display

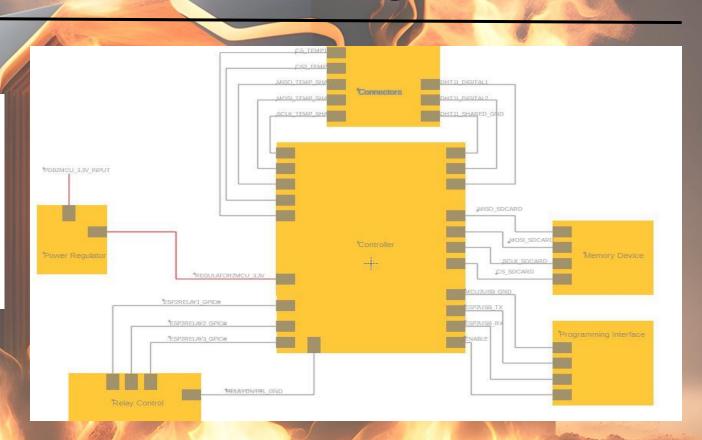
- Displays real time system status such as temp readings, heat modes, and safety alerts
- Allows user to interact with the system and control settings



Hardware Block Diagram

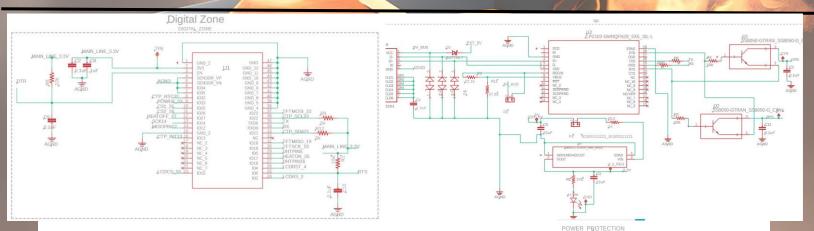
MCU Board

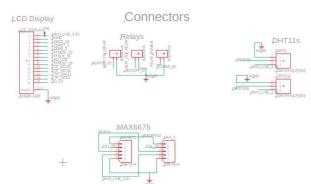
- → Main processor unit for our project
- → Power and communication to peripherals
- → Heat/ Low Power/ EMC

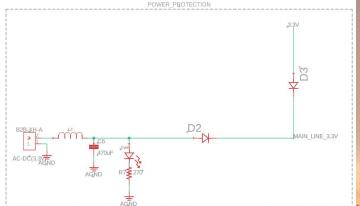


Overall Schematics (MCU)







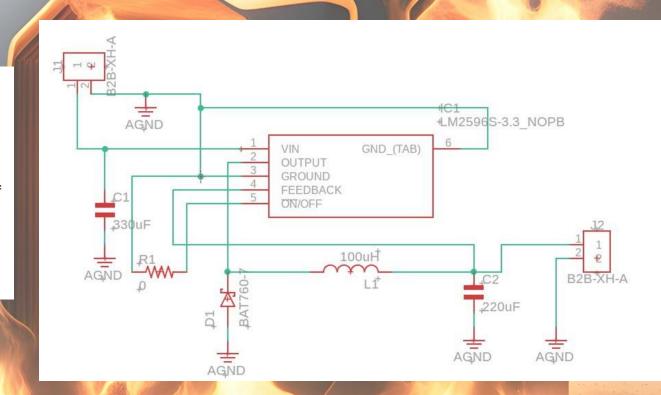




Overall Schematics (DC-DC)

Custom Power Supply

- → 12/24 Input, 3.3V Simple Switcher Buck Regulator
- → Continuous Mode of Operation
- → Low ESR Capacitors and Inductors Required

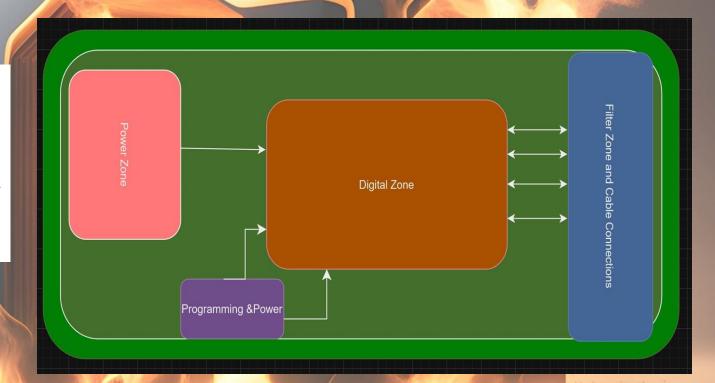




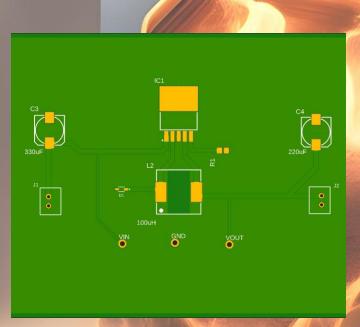


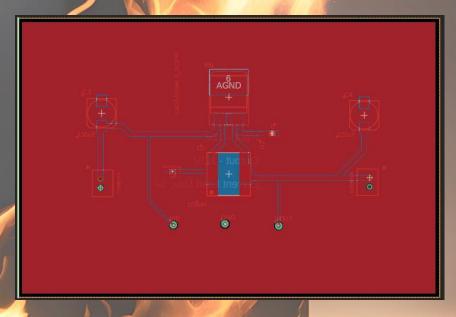
To Effectively Layout our PCB:

- → Take into account EMC considerations
- → Ensure signal/ power integrity
- → Solution: PCB Zones



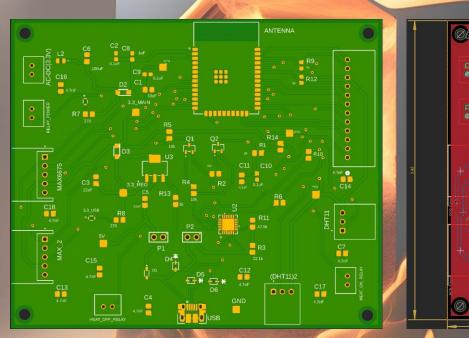
PCB Layout (DC-DC Converter)

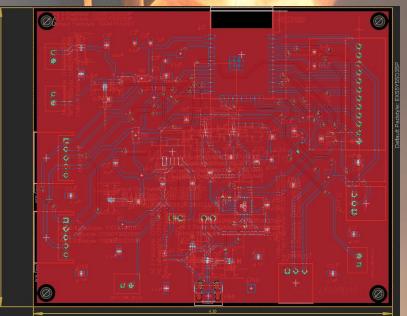




PCB Layout (MCU)



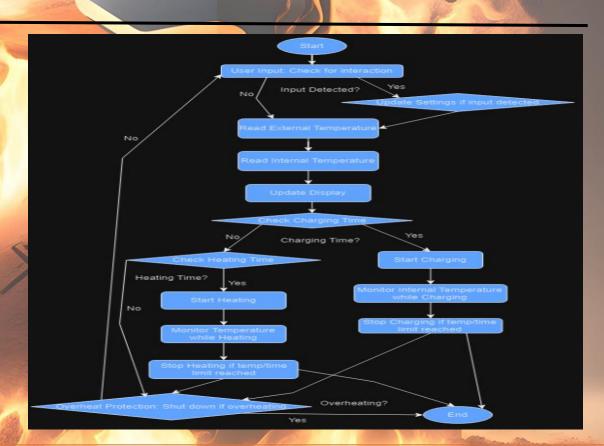








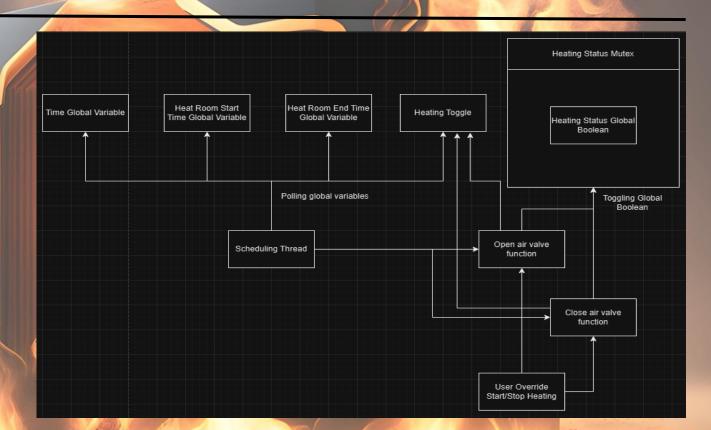
→ Front end display main and setting software flow chart







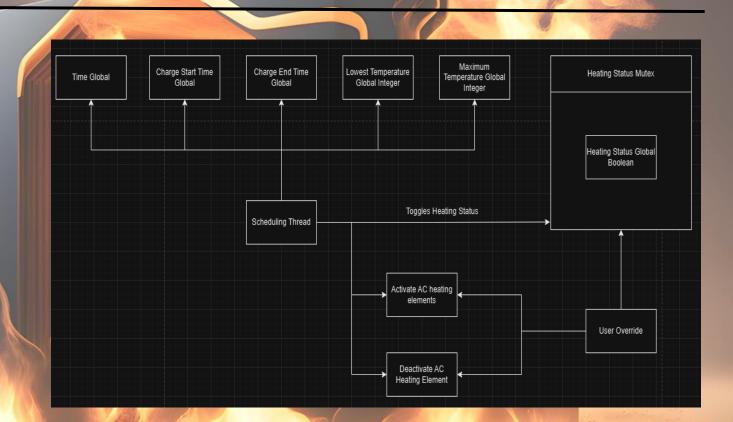
→ Heating Status Scheduling Thread







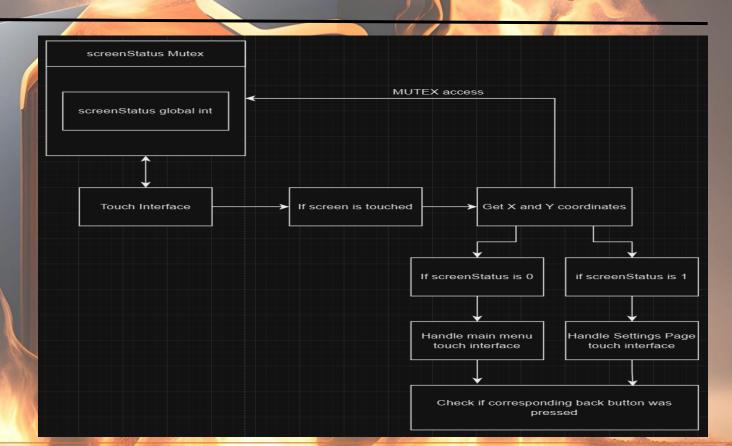
→ Charging
Status
Scheduling
Thread







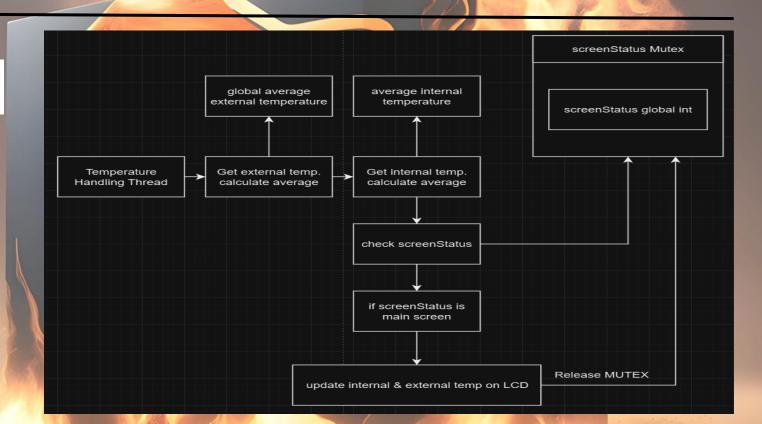
→ Touch Interface Thread







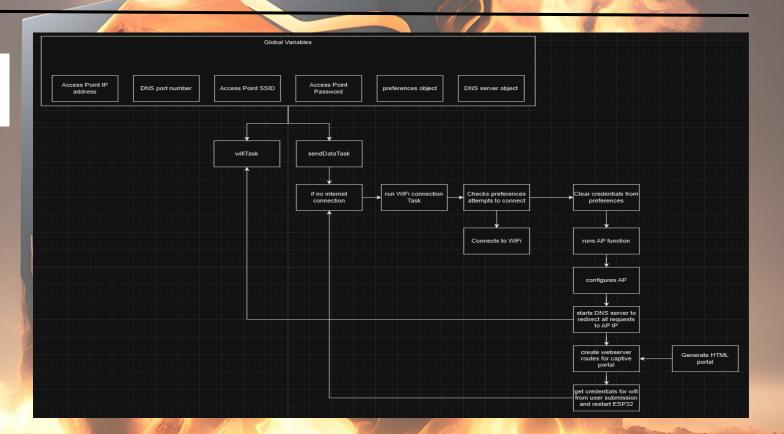
→ Temperature Readings







→ Wifi
Connection
Thread



Prototyping and Testing

- → Testing DHT11's
- → K-Type Thermocouples
- → LCD Display
- → Wifi Connectivity
- → Relay Control



- → Testing to see how long battery takes to reach full charge
- → Testing to see how long battery takes to full discharge
- → Test maximum overall system power draw

Prototyping and Testing



Hardware Test Procedure:

- 1. Preliminary:
 - a. Visual Inspection
 - b. Continuity Checks across critical power and ground points
 - c. Power-Up Test
 - d. Communication Verification to MCU
 - e. Peripheral Testing





Hardware Test Procedure:

- 2. Functional Tests
 - Verify that the PCB can read from all sensors and can accurately execute the code as intended
 - Verify the LCD display can be integrated with touch capabilities
 - Signal Lines will be probed to evaluate the integrity. Here we check for signal degradation, noise, rise and fall times
 - Power Lines will be probed for accurate voltage and current draws





Hardware Test Procedure:

- 3. ESS Testing
 - Unit Under Test (UUT) will be tested under a load similar to what is expected for demo
 - UUT will then be tested to extended periods of time to observe any power
 & communication failures and/or overheating
 - Data will be gathered to establish performance limits and trends

Successful Evaluation



To qualify as a success, the hardware must pass the following acceptance criteria:

- Correct functionality in reference to our stated goals
- Stable power outputs
- No communication failures
- Boards can effectively operate within safe operating temperatures. Thermal management devices were be added (heatsinks)





Budget

- → Final Budget: \$910
- → Goal: Provide a low-cost heating solution
- → Beating the avg cost of a lithium battery per Kwh (\$300)

Systems	Budget
Frame/Sand Storage	\$200
MCU/Peripherals/Components	\$400
DC-DC Converter/Heater	\$150
Valves/Fans/Aesthetics	\$160
TOTAL	\$910



Work Distribution

Michael Hernandez

- SchematicCapture/ PCBDesign for MCU
- Parts Selection for cable assemblies
- Hardware Integration

Miguel Baca-Urteaga

- Sensor and Communication Protocols
- Software Integration
- Software Testing and Validation

Filipe Pestana Frances

- LCD communication for MCU
- Graphic User Interface
- Touch Display Capabilities

Tanner Cyr

- Schematic
 Capture/PCB
 Design for AC-DC
 Converter
- Structural and Mechanical Design
- Welding and Manufacturing

<u>All:</u>

- Assembling PCBs
 Mechanical and Electronic Integration
- Soldering/Troubleshooting

 Verification & Validation

- System Level

Senior Design II Milestones





PCBs were fabricated and assembled

10/08/2024



Software was integrated onto boards, cable assemblies were made

10/15/24



V2 of the boards were demoed with enclosure prototype

> Midterm Demo



Final System design was assembled and tested throughly for functional goals and ready.

11/10/24



Final Review, SD Showcase, Exit Surveys.

We are here!

1-2 Weeks: Boards were assembled and tested





Enclosure design was was started



Final enclosure design was finished. Integration was started



Conducted routine checks. Finished final documentation/vide os 9 Weeks